



# PCI Express® Cabling Updates

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# Disclaimer

**The information in this presentation refers to specifications still in the development process. This presentation reflects the current thinking of various PCI-SIG® workgroups, but all material is subject to change before the specifications are released.**

# Current Cabling Status

- 1.0 Specification released Jan 2007
- 2.0 Specification releases Q3 2012 (estimated)
- 3.0 Specification working on SOA Q2 2012

# PCI Express® External Cable Connectors



x1

x4

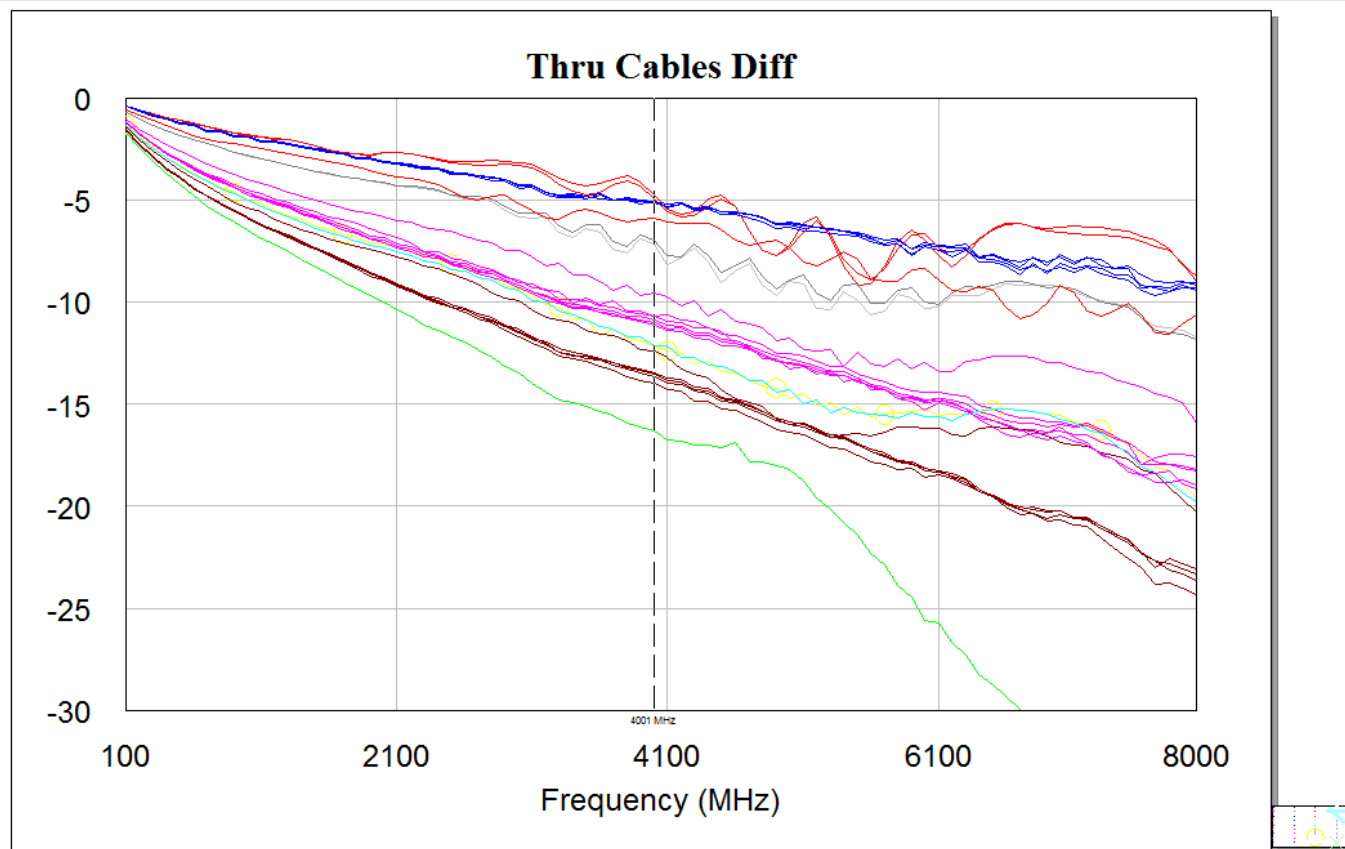
x8

x16

# Challenges for PCIe® 3.0

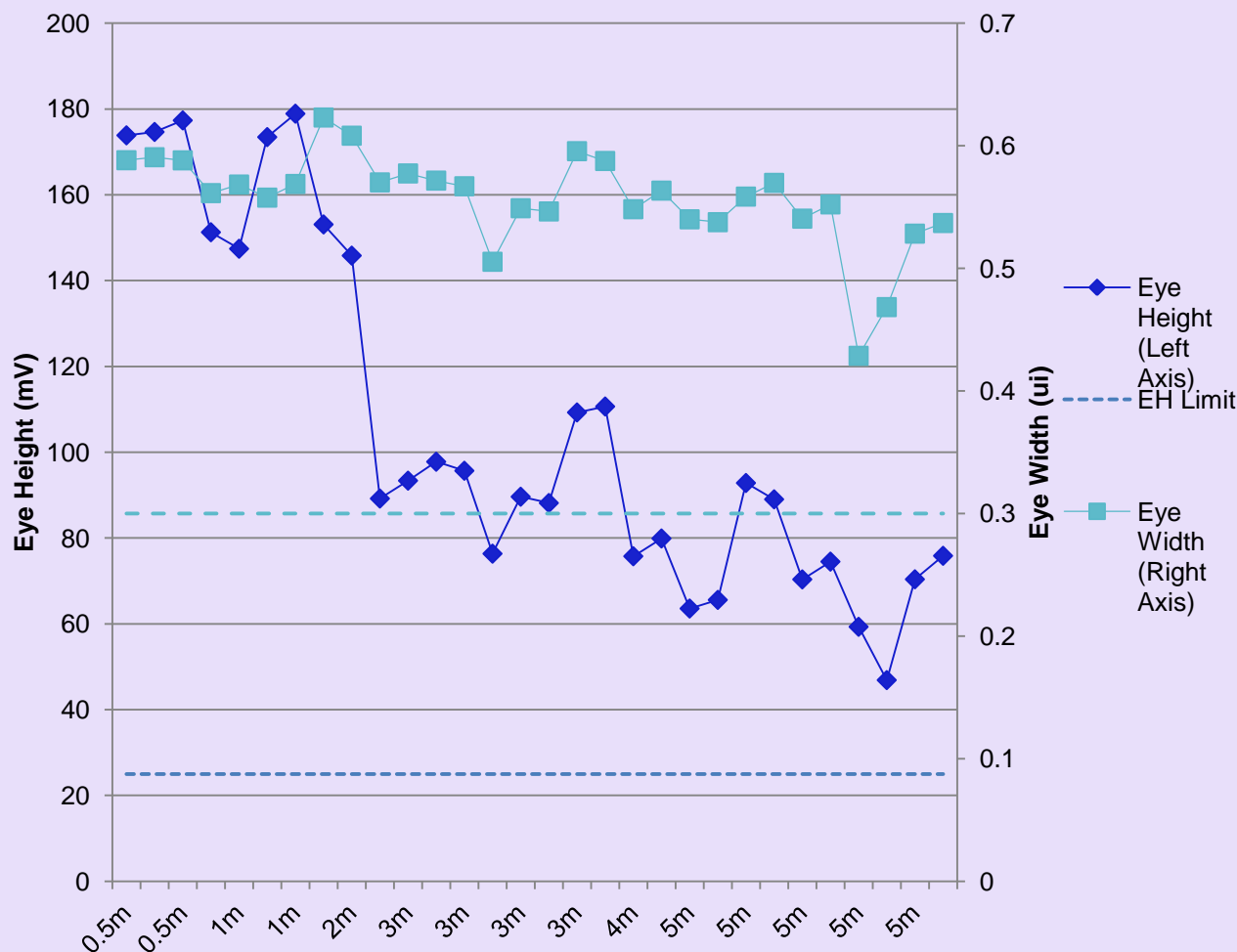
- Other than 8GT/s...
- Clocking
- Equalization
- Optics
- Compatibility

# Cable Losses



The spread of cable losses and board losses make a single setting for the equalization preset hints unlikely.

# Preliminary Simulation Results



Results indicate that passive cable lengths beyond 3m are possible.

More work needs to be done, these do not include crosstalk.

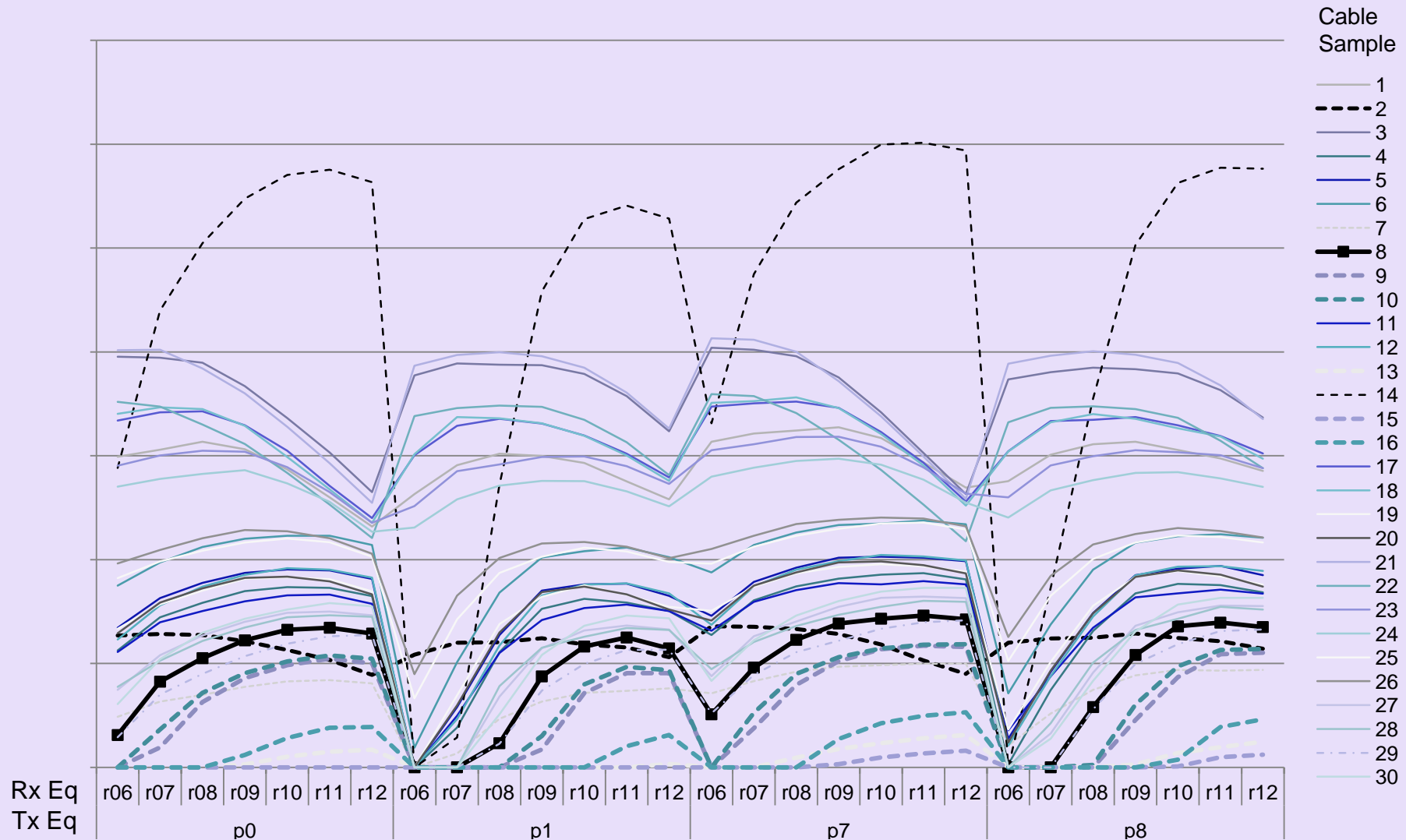
# Link Equalization Settings

- PCIe 3.0 cable needs presets to be able to establish minimal link to begin equalization negotiation
  - ✓ 4 phase process, beginning during PCIe 1.0 operation
    - First phase includes sending presets over the link to begin 8GT/s link operation at low BER. This value determined by system/board level designer during validation and programmed into device.
- Cable links have no pre-knowledge of system losses to set this preset hint
  - ✓ Preset may be too much or too little for any given cable to establish reliable link at 8GT/s



# Link Training for PCIe 3.0

## Overall Graph Data

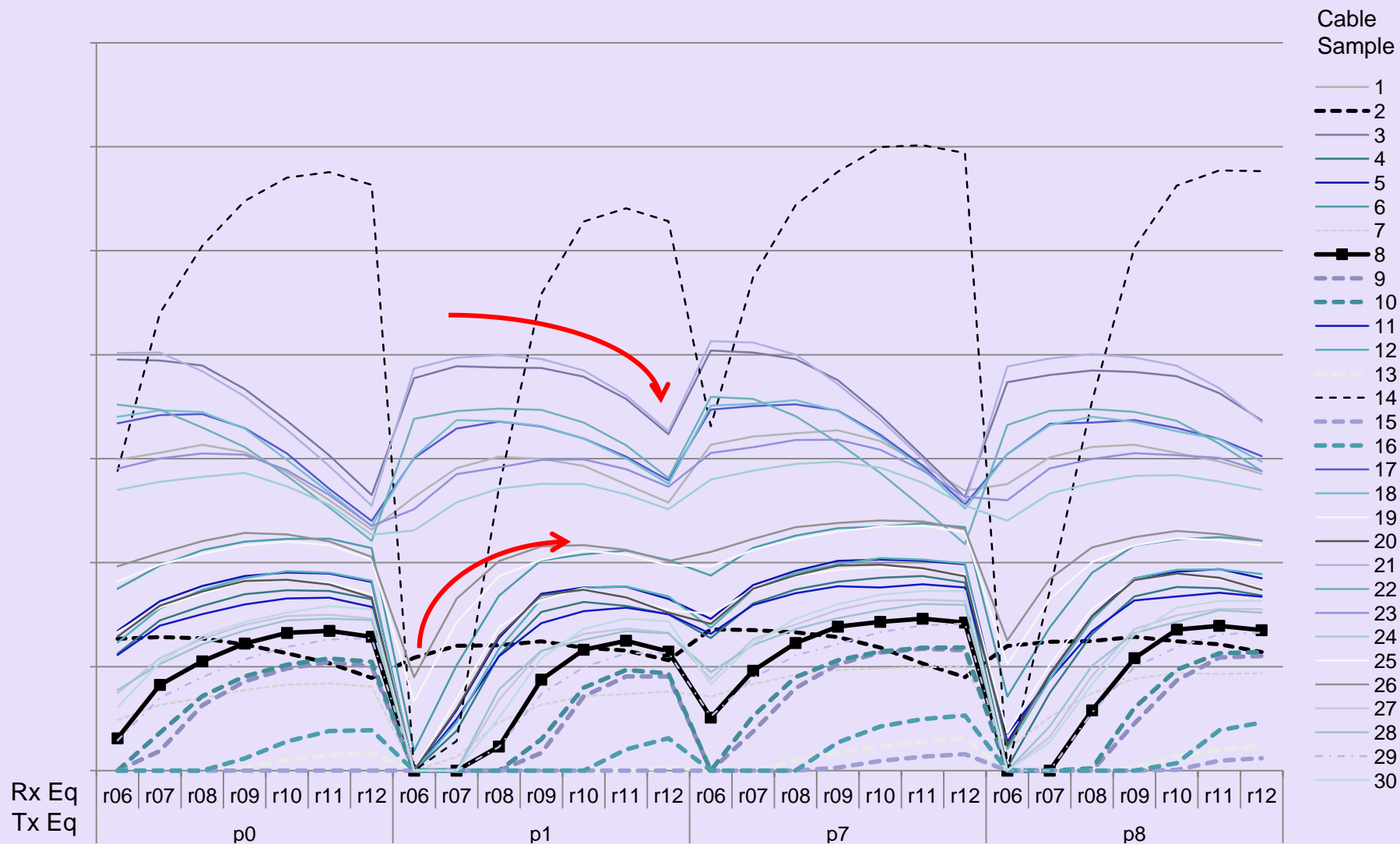


# Looking at the Data

- Some cables will train at any preset combination
- Different cable assemblies react differently to the transmitter and receiver settings
  - ✓ This can make finding a common setting difficult
- Data included only a single board configuration at either end. Real systems will have a much larger variety in link profile due to design of mating boards. This will need to be explored.

Note: Four presets shown represent the most common from other form factors

# Response Trends to Equalization for the Cable Assemblies



# Potential Solutions for Copper Cables

- Use single Tx setting for all cables
  - ✓ Potentially limits solution space
- Cable provide data to equalizers
  - ✓ Cable provides loss information to components for preset hints
- Active Copper
  - ✓ Cable can “remove” its own copper and dielectric loss
- Each solution has its own cost and complexity implications

# Providing Data to Equalizers

- Use i2c or other data transfer scheme to send data from cable to each end, or upstream only
  - ✓ Goal would be to provide a cable loss estimate that is translated into preset hints and sent to the devices
  
- One problem, x4 cable has no extra pins
  - ✓ Multiplex existing sidebands?
  - ✓ Re-pin the cable for PCIe 3.0?
  - ✓ Change connector?

# Active Copper Cables

- Participate in, or ignore, Tx change requests?
- Repeaters and External Equalizers are not specifically comprehended in the specification
- And optical links will have this issue as well...

# Optical PCI Express Challenges and Considerations

- No sidebands over fiber
  - ✓ Optical sidebands are very expensive
  - ✓ Mixed technology cables are possible, but this increases complexity and removes electrical isolation
- No additional cable pins available in current solution for active cable programming/identification
- Separate Refclk architecture
  - ✓ Currently only a couple of devices can do this
  - ✓ Some optical solutions handle this with varying degrees of success
  - ✓ New ECR is being evaluated, but implementation is unknown
  - ✓ Some solutions use a non-spread clock for optical solution

# Optical PCI Express Challenges and Considerations

- Electrical Idle support
  - ✓ What happens to optics during electrical idle?
- Presence Detect
- Link EQ negotiations
  - ✓ Equalization behaviors
- Cascading Jitter
- Data Flow
  - ✓ Credits, Ack/Nack Timeouts, Completion Timeouts due to time-of-flight
  - ✓ Loss of throughput/data bandwidth due to credits



# Optical PCI Express Challenges and Considerations

- Which optical form factor?
  - ✓ Active optical cable
  - ✓ optical module (i.e. SFP, CFP, etc.)
  - ✓ Integrated optics with external fiber cable
- Power & Thermal Density for x16 cables appears to be difficult

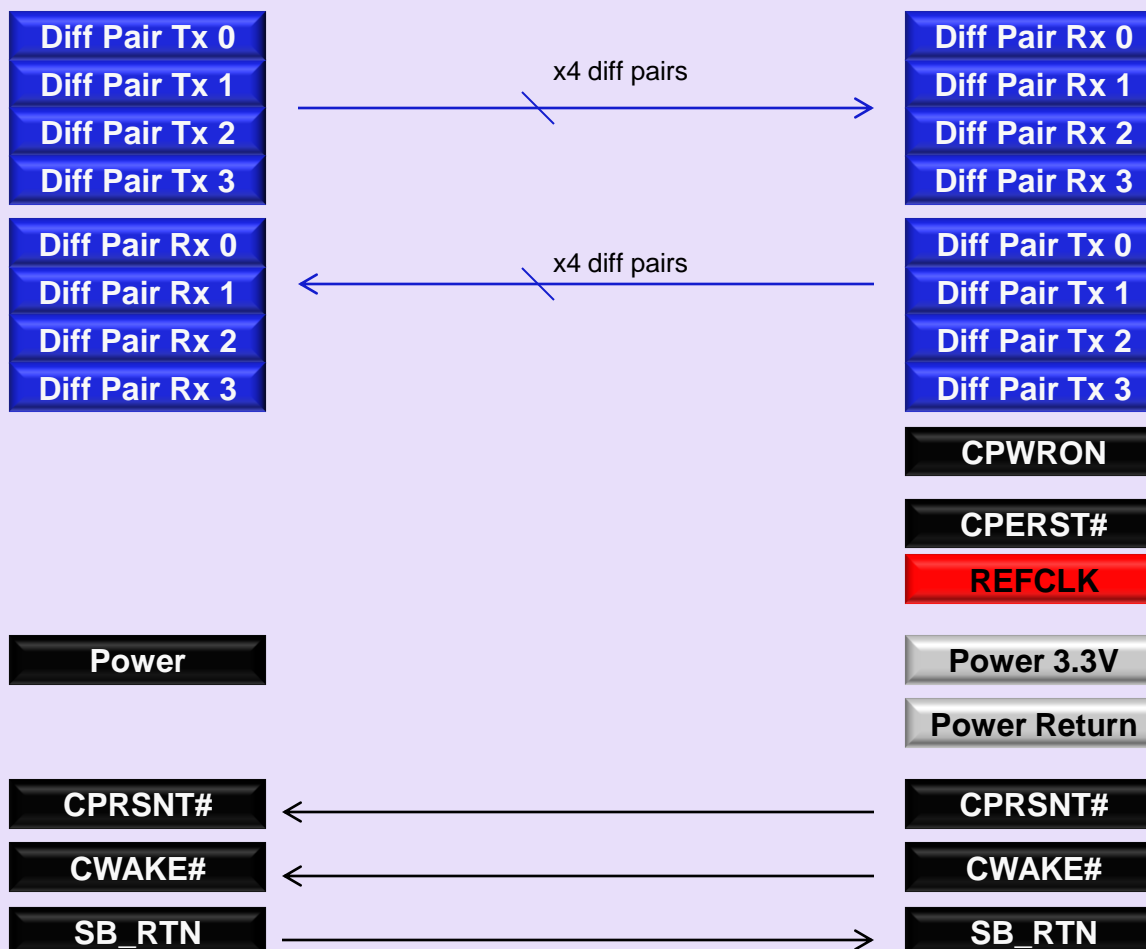
# Compatibility

- A new cable group has been tasked with creating a smaller form factor to support mobile applications
  - ✓ Current cable connectors are too large
- The new group is intending to support separate Reference clocks
  - ✓ This will not work with existing cabled products
- Sideband support
  - ✓ There is an attempt to minimize sidebands, but the specifics are in development

# Port Signal Mismatch

## Upstream OCuLink Port

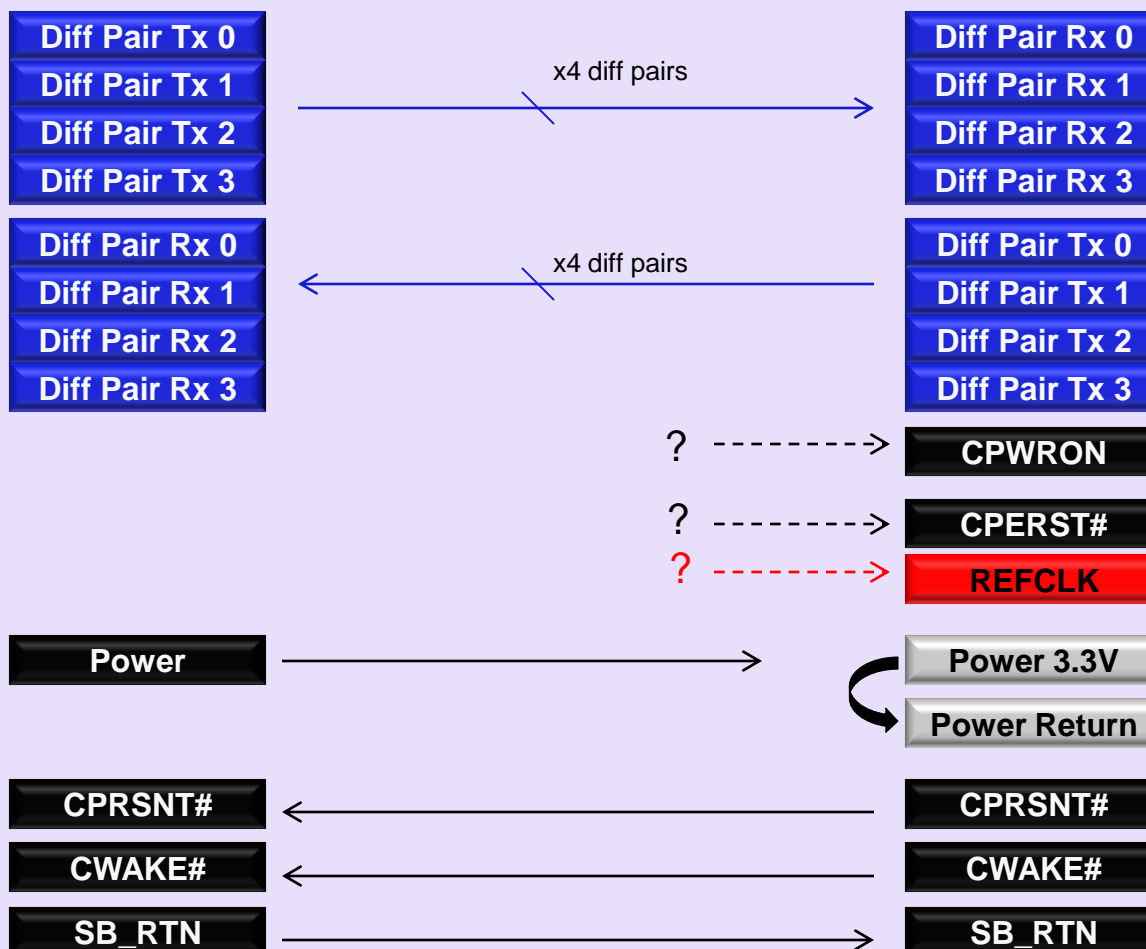
## Downstream Legacy PCIe Port



# Port Signal Mismatch

Upstream OCuLink Port

Downstream Legacy PCIe Port



# Cabled PCIe 3.0 Options

- Stay with current PCIe cable connectors
  - ✓ Reuse existing sideband pins
  - ✓ Exclude x4 from PCIe 3.0
- New Connector
  - ✓ Allows modularity
    - Ability to down-plug a port without a special cable
  - ✓ Optical support in the same connector
- Architectural Compatibility
  - ✓ OCuLink
  - ✓ Legacy PCIe
- Equalization Scheme

# Call to Action

- Review your company's cabling needs and share with the Cabling Working Group. There is time to have your voice heard.



# PCI Express® Cabling Updates

**Michael Krause**  
**OCuLink Workgroup Chair**  
**Hewlett-Packard**



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# What is OCuLink?

- New specification effort targeting:
  - ✓ Small form factor optimized connectors
  - ✓ Internal enclosure cable usage models
  - ✓ External enclosure cable usage models

# External Usage Models

## ■ External enclosures

- ✓ Ultra-thin mobile
- ✓ Desktop / workstation
- ✓ All-in-one computers
- ✓ I/O expansion enclosure



## ■ Peripherals

- ✓ Audio / Video equipment (camera, microphones, etc.)
- ✓ Video distribution
- ✓ Monitor hub
- ✓ Medical equipment
- ✓ External storage
- ✓ Docking stations



# Internal Usage Models

- Internal enclosures
  - ✓ Ultra-thin mobile
  - ✓ Desktop / workstation
  - ✓ Server and storage arrays
- Peripherals
  - ✓ Storage disk drives
  - ✓ NVM / solid state storage drives and adapters
  - ✓ I/O expansion slots



# Cable Types and Distances

- Passive copper cable solutions
  - ✓ ~1-2 meters
- Active copper cable solutions
  - ✓ ~2-10 meters
- Active optical cable solutions
  - ✓ ~1-N meters
    - N can be quite large, e.g. 100-300 meters
    - Primarily limited by optics technology and mechanical packaging
      - Also limited by PCIe protocol timeouts (no extreme optical distances)
- Optional peripheral power
  - ✓ ~10W peripheral
  - ✓ ~3W for active module components
  - ✓ Power from either end or both (long distance active)

# Connector Attributes (1)

- Single external connector size
  - ✓ Symmetrical cable
- Single internal connector size
  - ✓ Symmetrical cable
- Maximum link width of x4
  - ✓ Implementations can support x1, x2, or x4
  - ✓ Optional aggregated cables to create x8/x16 solutions
- All implementations must support 2.5, 5, 8 GT/s
  - ✓ Will scale to PCI Express® 4.0 (current target 16 GT/s)
- Optional peripheral power support
  - ✓ 5V, Vaux 3.3V

# Connector Attributes (2)

- Minimal sideband signals
  - ✓ CPRSNT#, SB-RTN, CWAKE#
- No Refclk
  - ✓ Requires independent clock with SSC ECN
- Durability
  - ✓ External connector – 10K
  - ✓ Internal connector – 50
- Retention mechanism – Yes, method TBD
- No impact to software, i.e. cable is transparent
- No daisy chain mechanical support
  - ✓ Daisy chain accomplished using a 3-port PCIe® Switch and two connectors within the enclosure and two cables

# Current Status

- Draft 0.3 Review – Completed
- Draft 0.5 Review – Underway
- Connector Concept Evaluation – Underway
- Draft 0.7 Review – target 3Q2012
- Draft 0.9 Review – target late 4Q2012
- Final specification 1Q2013

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